



EP5087 THERMALLY CONDUCTIVE EPOXY ADHESIVE

● PRODUCT DESCRIPTION

EP5087 is a two-component fast curing thermally conductive adhesive, sealant and potting compound. It is designed to deploy heat in electronic applications, with a measured thermal conductivity of 1.5 W/mK. Suitable for metal, plastics, ceramics and ferrite bonding applications.

● CURING PROPERTIES

Work Life @ 25°C	Gel Time @ 25°C	Full Cure
10 min	60 min	@ 25° C 24 hours
		@ 65° C 60 min

● PHYSICAL PROPERTIES

Color	Gray	
Viscosity (mixed)	Part A	Part B
	Paste	35000 Cps
Specific Gravity	2,35	
Mix ratio (by weight or volume)	1:1	

● INSTRUCTIONS FOR USE

Temperature Resistance (°C)	-40 to +150
Hardness Shore D	75
Lap Shear Strength (Psi)	1600
Thermal Conductivity (W/mK)	1,5
Elongation at Break	25%
Tg (°C)	56
Volume Resistivity	
• 100 V (Ω-cm)	8.0 x 10 ¹⁴
• 500 V (Ω-cm)	6.3 x 10 ¹⁴
Dielectric Constant	
• 120 Hz	4.3
• 1000 Hz	4.3
Dissipation Factor	
• 120 Hz	0.002
• 1000 Hz	0.002





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• INSTRUCTIONS FOR USE

The surfaces should be free of dust, oil and other dirt in order to obtain an optimal efficient bond.

Shelf life: Store in original, unopened containers for 12 months at room temperature

The resin of part B might cristalize during storage. This process is reversible by heating (1 hour @ 60°C).

